

**N&P-Channel MOSFET** 

## **General Description**

The WSP4067B is the highest performance trench N-ch and P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSP4067B meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

### **Product Summery**

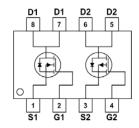
BVDSS	RDSON	ID
40V	25mΩ	6.0A
-40V	40mΩ	-5.1A

### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter.
- Networking DC-DC Power System
- Load Switch

### **SOP-8 Pin Configuration**





### **Absolute Maximum Ratings**

		Rat		
Symbol	Parameter	N-Channel	P-Channel	Units
$V_{DS}$	Drain-Source Voltage	40	-40	V
$V_{GS}$	Gate-Source Voltage	±20	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current	6.0	-5.1	А
I <sub>D</sub> @T <sub>C</sub> =70℃	Continuous Drain Current	3.9	-3.2	Α
I <sub>DM</sub>	Pulsed Drain Current	24	-20	А
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation	2	2	W
T <sub>J</sub> /T <sub>STG</sub>	Operating Temperature /Storage Temperature Range -55 to 150		$^{\circ}$	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62.5	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		50	°C/W



**N&P-Channel MOSFET** 

# N-Channel Electrical Characteristics (T<sub>J</sub>=25 <sup>™</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.067		V/°C
D	Static Drain-Source On-Resistance	$V_{GS}$ =10V , $I_D$ =6A		25	35	0
R <sub>DS(ON)</sub>	Static Dialii-Source Off-Resistance	$V_{GS}$ =4.5 $V$ , $I_D$ =5 $A$		40	55	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . I <sub>D</sub> =250uA	1.0	1.6	2.2	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> -2500A		-5.24		mV/℃
-	Drain Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =85℃			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =85℃			30	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
Qg	Total Gate Charge			11		nC
$Q_gs$	Gate-Source Charge	$V_{DS}$ =20V , $V_{GS}$ =10V , $I_{D}$ =6A		2		
$Q_gd$	Gate-Drain Charge			2.2		
T <sub>d(on)</sub>	Turn-On Delay Time			1.9		
Tr	Rise Time	$V_{DS} = 20 \text{ V}, V_{GEN} = 10 \text{ V},$ $R_G = 3.3 \Omega, R_I = 3.3 \Omega,$		18.6		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>DS</sub> = 6 A .		8.7		ns
T <sub>f</sub>	Fall Time			2.6		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		600		
C <sub>oss</sub>	Output Capacitance			62		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			48		

### **Diode Characteristics**

ı	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
	I <sub>S</sub>	Continuous Source Current	TA=25°C.			2.6	Α
Ī	$V_{SD}$	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A			1.3	V

A: The value of R  $_{\theta}$  JA is measured with the device mounted on 1in $^{2}$  FR-4 board with 2oz. Copper, in a still air environment with TA=25°C. The value in any given application depends on the user's specific board design.

 $<sup>\</sup>hbox{B: Repetitive rating, pulse width limited by junction temperature.}\\$ 

C: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.



### **N&P-Channel MOSFET**

# P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =-1mA		-0.03		V/°C
D	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V , I <sub>D</sub> =-4A		40	50	m()
R <sub>DS(ON)</sub>	Static Dialii-Source Off-Resistance	V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A		55	75	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250uA$	-1.0	-1.6	-2.2	V
la co	Drain Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =85℃			-1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =85℃			-30	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
Qg	Total Gate Charge			20		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =-20V , $V_{GS}$ =-10V , $I_{D}$ =-5.1A		5.7		nC
Q <sub>gd</sub>	Gate-Drain Charge			4.6		
T <sub>d(on)</sub>	Turn-On Delay Time			6.8		
Tr	Rise Time	$V_{DD}$ =-20V , $V_{GS}$ =-10V ,		33		
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=3.3\Omega$ , $I_D=-5.1A$ , $R_L=3.9\Omega$ .		30		ns
T <sub>f</sub>	Fall Time			12		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		1100		
C <sub>oss</sub>	Output Capacitance			100		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			80		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	TA=25°C.			-2.6	Α
$V_{SD}$	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A .			-1.2	V

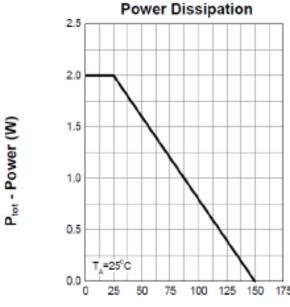
A: The value of Rejais measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with Ta=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

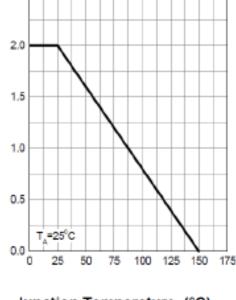
C: The current rating is based on the  $t \le 10s$  junction to ambient thermal resistance rating.

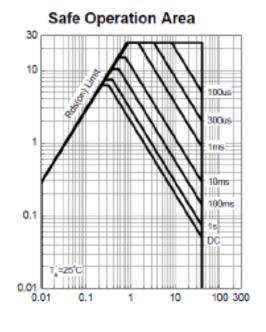


# **N-Channel Typical Characteristics**



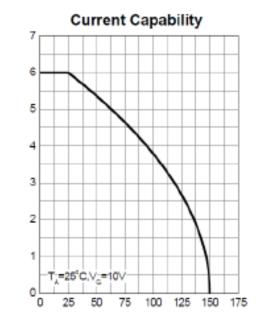
T<sub>i</sub> - Junction Temperature (°C)



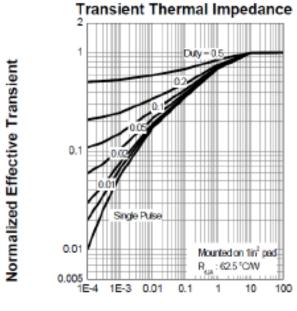


Io - Drain Current (A)

V<sub>DS</sub> - Drain-Source Voltage (V)



T<sub>i</sub> - Junction Temperature(°C)



Square Wave Pulse Duration (sec)

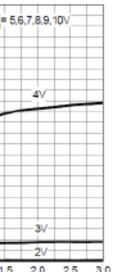
I<sub>D</sub> - Drain Current (A)



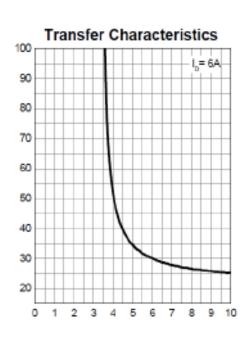
I<sub>o</sub> - Drain Current (A)

R<sub>DS(ON)</sub> - On Resistance (mΩ)

Output Characteristics 24 22 20 18 16 14 12 10 8 6



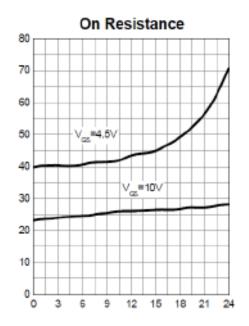
V<sub>DS</sub> - Drain-Source Voltage (V)



V<sub>GS</sub> - Gate-Source Voltage (V)



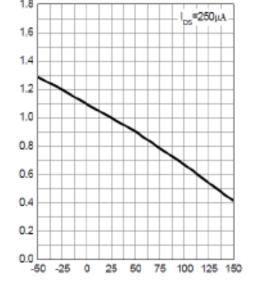




I<sub>D</sub> - Drain Current (A)

Normalized Threshold Voltage



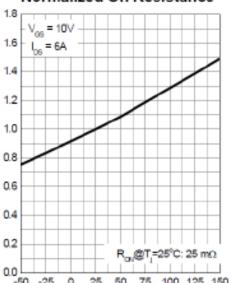


T<sub>I</sub> - Junction Temperature (°C)



Normalized On Resistance

Normalized On Resistance

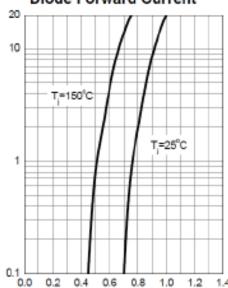


-50 -25 0 25 50 75 100 125 150

T<sub>i</sub> - Junction Temperature (°C)

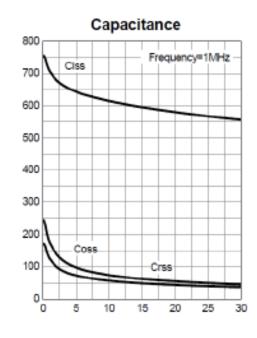
Is - Source Current (A)

Diode Forward Current



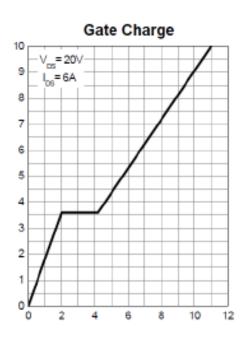
V<sub>SD</sub> - Source-Drain Voltage (V)

: - Capacitance (pF)



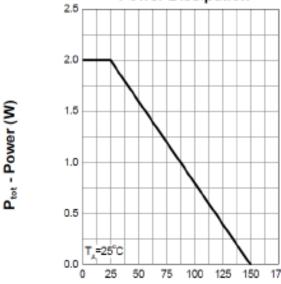
V<sub>DS</sub> - Drain-Source Voltage (V)

V<sub>GS</sub> - Gate-Source Voltage (V)



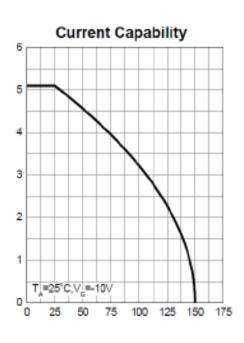
Q<sub>G</sub> - Gate Charge (nC)





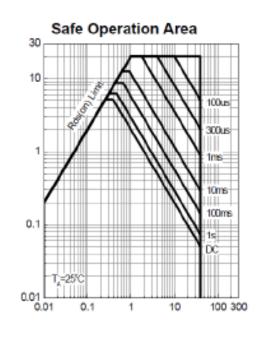
Power Dissipation

-lo - Drain Current (A)



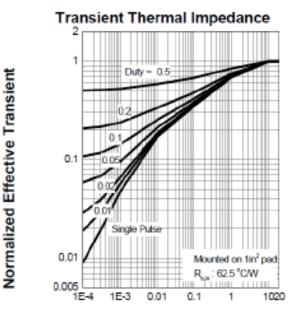
T<sub>j</sub> - Junction Temperature (°C)

T<sub>j</sub> - Junction Temperature (°C)



-I<sub>o</sub> - Drain Current (A)

- VDS - Drain-Source Voltage (V)



Square Wave Pulse Duration (sec)



-Io - Drain Current (A)

Output Characteristics

30

25

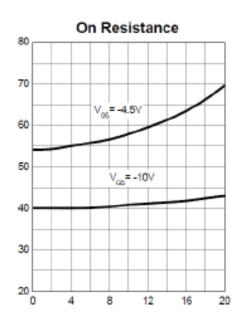
20

-4V

00.0 0.5 1.0 1.5 2.0 2.5 3.0

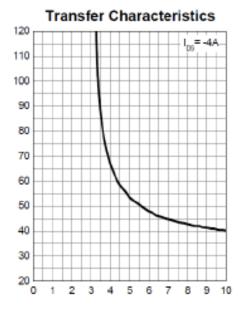
-VDS - Drain-Source Voltage (V)

R<sub>DS(ON)</sub> - On Resistance (mΩ)



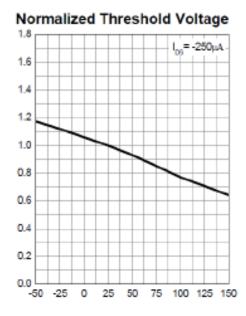
-ID - Drain Current (A)

RDS(ON) - On Resistance (mQ)



-V<sub>GS</sub> - Gate-Source Voltage (V)

Normalized Threshold Voltage



T<sub>j</sub> - Junction Temperature (°C)

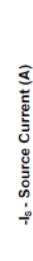


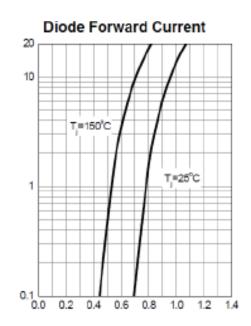
Normalized On Resistance

C - Capacitance (pF)

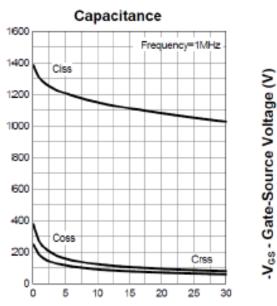
# Normalized On Resistance 1.8 V<sub>08</sub> = -10V 1.6 -1<sub>DS</sub> = -4A 1.4 1.2 1.0 0.8 0.6 0.4 R<sub>ov</sub>@T<sub>j</sub>=25°C; 40 mΩ 0.2 -50 -25 0 25 50 75 100 125 150

T<sub>j</sub> - Junction Temperature (°C)

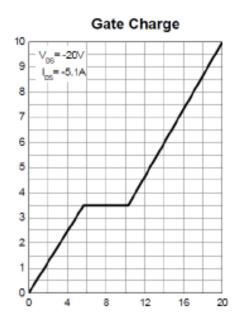




-V<sub>SD</sub> - Source-Drain Voltage (V)



-VDS - Drain-Source Voltage (V)



Q<sub>G</sub> - Gate Charge (nC)



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1
DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 IPSA70R950CEAKMA1 IPSA70R2K0CEAKMA1 STU5N65M6
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